

# BGA777N7

Single-Band UMTS LNA (2300 - 2700 MHz)

## Data Sheet

Revision 3.1, 2013-01-31

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**BGA777N7 Single-Band UMTS LNA (2300 - 2700 MHz)**

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Page	Subjects (major changes since last revision)
33	Footprint recommendation drawing added
34	Marking pattern drawing updated

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## 1 Features

Main features:

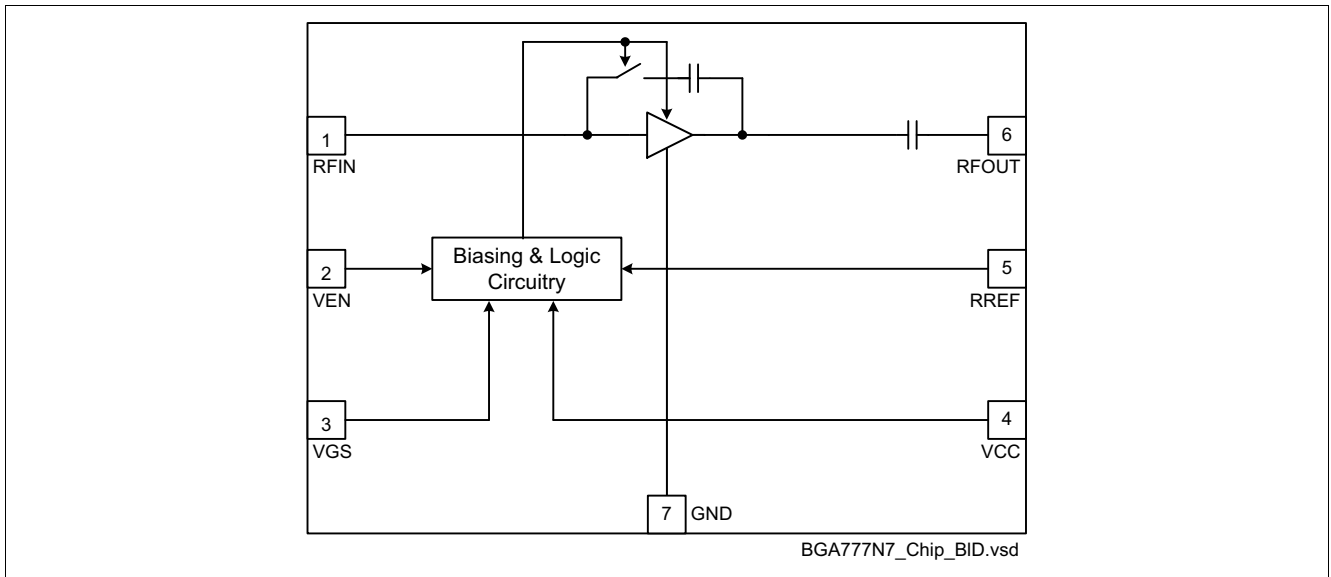
- Gain: 16 / -7 dB in high / low gain mode
- Noise figure: 1.2 dB in high gain mode
- Supply current: 4.2 / 0.5 mA in high / low gain mode
- Standby mode (< 2  $\mu$ A typ.)
- Output internally matched to 50  $\Omega$
- Inputs pre-matched to 50  $\Omega$
- 2 kV HBM ESD protection
- Low external component count
- Small leadless TSNP-7-1 package (2.0 x 1.3 x 0.39 mm)
- Pb-free (RoHS compliant) package



### Description

The BGA777N7 is a low current single-band low noise amplifier MMIC for UMTS bands 7, 38 and 40. The LNA is based upon Infineon's proprietary and cost-effective SiGe:C technology and comes in a low profile TSNP-7-1 leadless green package. This document specifies electrical parameters, pinout, application circuit and packaging of the chip. The device features dynamic gain control, temperature stabilization, standby mode and 2 kV ESD protection on-chip as well as matching off chip.

Product Name	Package	Chip	Marking
BGA777N7	TSNP-7-1	T1531	B7



**Figure 1** Block Diagram of Single-Band LNA



## 2 Electrical Characteristics

### 2.1 Absolute Maximum Ratings

**Table 1 Absolute Maximum Ratings**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Supply voltage	$V_{CC}$	-0.3	–	3.6	V	–
Supply current	$I_{CC}$	–	–	10	mA	–
Pin voltage	$V_{PIN}$	-0.3	–	$V_{CC}+0.3$	V	All pins except RF input pins.
Pin voltage RF Input Pins	$V_{RFIN}$	-0.3	–	0.9	V	–
RF input power	$P_{RFIN}$	–	–	4	dBm	–
Junction temperature	$T_j$	–	–	150	°C	–
Ambient temperature range	$T_A$	-30	–	85	°C	–
Storage temperature range	$T_{stg}$	-65	–	150	°C	–

**Attention: Stresses above the max. values listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Maximum ratings are absolute ratings; exceeding only one of these values may cause irreversible damage to the integrated circuit.**

### 2.2 Thermal Resistance

**Table 2 Thermal Resistance**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance junction to soldering point	$R_{thJS}$	–	240	–	K/W	–

### 2.3 ESD Integrity

**Table 3 ESD Integrity**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
ESD hardness HBM <sup>1)</sup>	$V_{ESD-HBM}$	–	2000	–	V	All pins

1) According to JESD22-A114

## 2.4 DC Characteristics

**Table 4 DC Characteristics,  $T_A = -30 \dots 85 \text{ }^\circ\text{C}$**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Supply voltage	$V_{CC}$	2.6	2.8	3.0	V	–
Supply current high gain mode	$I_{CCHG}$	2.8	4.2	5.8	mA	
Supply current low gain mode	$I_{CCLG}$	0.2	0.53	0.8	mA	
Supply current standby mode	$I_{CCOFF}$	-0.5	0.1	2.0	$\mu\text{A}$	–
Logic level high	$V_{HI}$	1.5	2.8	3.0	V	All logic pins
Logic level low	$V_{LO}$	-0.2	0.0	0.5	V	
Logic currents	$I_{LO}$	-0.5	0.01	2.0	$\mu\text{A}$	All logic pins
	$I_{HI}$	4.0	5.0	6.0	$\mu\text{A}$	

## 2.5 Gain Mode Select Truth Table

**Table 5 Truth Table**

Control Voltage		State	
		Bands 7, 38, 40	
VEN	VGS	HG	LG
H	L	OFF	ON
H	H	ON	OFF
L	L	STANDBY <sup>1)</sup>	
L	H		

1) In order to achieve minimum standby current it is encouraged to apply logic low-level at the VGS pin in standby mode although this is not mandatory. Details see section 2.4.

## 2.6 Switching Times

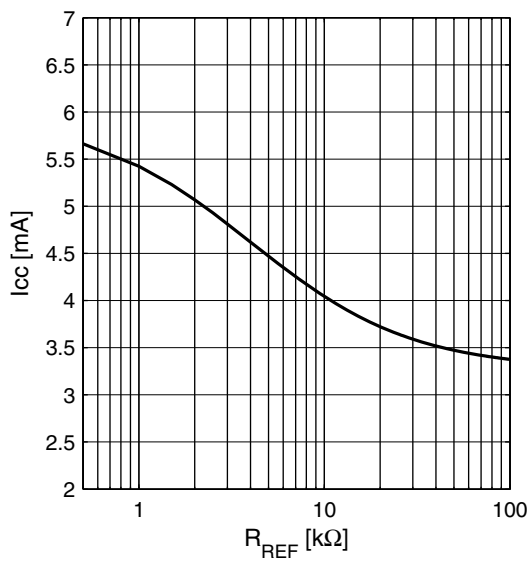
**Table 6 Typical switching times;  $T_A = -30 \dots 85 \text{ }^\circ\text{C}$**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Settling time gainstep	$t_{GS}$	–	1	5	$\mu\text{s}$	Switching LG $\leftrightarrow$ HG

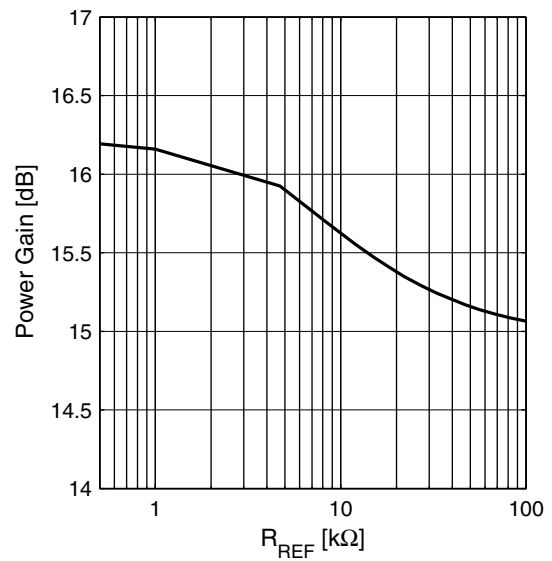
## 2.7 Supply Current Characteristics

Supply current high gain mode versus resistance of reference resistor  $R_{REF}$  (see Figure 2 on Page 28; low gain mode supply current is independent of reference resistor).

**Supply Current**  $I_{CC} = f(R_{REF})$   
 $V_{CC} = 2.8 \text{ V}$ ,  $T_A = 25 \text{ }^\circ\text{C}$



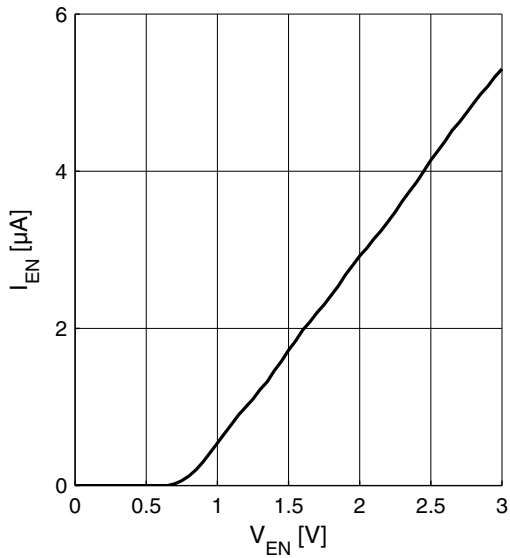
**Power Gain**  $|S_{21}| = f(R_{REF})$   
 $V_{CC} = 2.8 \text{ V}$ ,  $T_A = 25 \text{ }^\circ\text{C}$



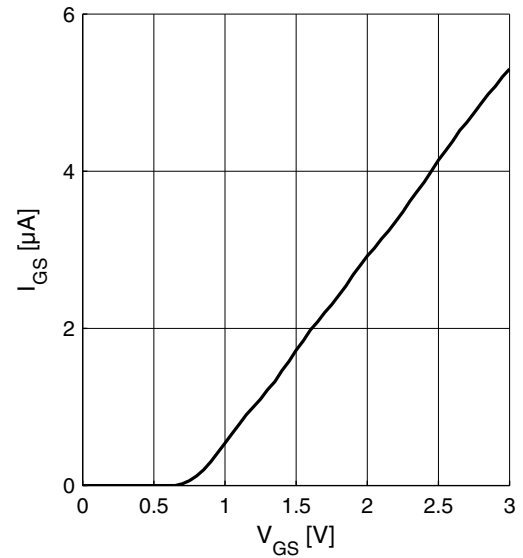
## 2.8 Logic Signal Characteristics

Current consumption of logic inputs VEN, VGS

**Logic Current  $I_{EN} = f(V_{EN})$**   
 $V_{CC} = 2.8 \text{ V}$ ,  $T_A = 25 \text{ }^\circ\text{C}$



**Logic Current  $I_{GS} = f(V_{GS})$**   
 $V_{CC} = 2.8 \text{ V}$ ,  $T_A = 25 \text{ }^\circ\text{C}$



## 2.9 Measured RF Characteristics UMTS Band 7

**Table 7** Typical Characteristics 2650 MHz Band,  $T_A = -30\text{ °C}$ ,  $V_{CC} = 2.8\text{ V}^{1)2)}$

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Pass band range band VII		2620	–	2690	MHz	–
Current consumption	$I_{CCHG}$	2.8	3.4	4.0	mA	High gain mode
	$I_{CCLG}$	0.2	0.5	0.8	mA	Low gain mode
Gain	$S_{21HG}$	14.5	16.0	17.5	dB	High gain mode
	$S_{21LG}$	-8.8	-6.3	-3.3	dB	Low gain mode
Reverse Isolation	$S_{12HG}$	–	-34	-25	dB	High gain mode
	$S_{12LG}$	-8.8	-6.3	-3.3	dB	Low gain mode
Noise figure	$NF_{HG}$	0.6	0.9	1.4	dB	High gain mode
	$NF_{LG}$	3.3	6.3	8.8	dB	Low gain mode
Input return loss	$S_{11HG}$	–	-16	-10	dB	50 $\Omega$ , high gain mode
	$S_{11LG}$	–	-11	-9	dB	50 $\Omega$ , low gain mode
Output return loss	$S_{22HG}$	–	-16	-10	dB	50 $\Omega$ , high gain mode
	$S_{22LG}$	–	-10	-8	dB	50 $\Omega$ , low gain mode
Stability factor	$k$	>1	>2.3	–		DC to 8 GHz; all gain modes
Input compression point	$IP_{1dBHG}$	-16	-9	–	dBm	High gain mode
	$IP_{1dB LG}$	-10	-2	–	dBm	Low gain mode
Inband IIP3 $f_1 - f_2 = 1\text{ MHz}$	$IIP3_{HG}$	-9	-2	–	dBm	High gain mode
	$IIP3_{LG}$	-7	5	–	dBm	Low gain mode

1) Performance based on application circuit in Figure 2 on Page 28

2) Guaranteed by device design; not tested in production.

## 2.10 Measured RF Characteristics UMTS Band 7

**Table 8** Typical Characteristics 2650 MHz Band,  $T_A = 25\text{ °C}$ ,  $V_{CC} = 2.8\text{ V}^{1)}$

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Pass band range band VII		2620	–	2690	MHz	–
Current consumption	$I_{CCHG}$	3.6	4.2	4.8	mA	High gain mode
	$I_{CCLG}$	0.3	0.53	0.7	mA	Low gain mode
Gain	$S_{21HG}$	14.4	15.7	17.0	dB	High gain mode
	$S_{21LG}$	-9.6	-7.1	-4.1	dB	Low gain mode
Reverse Isolation <sup>2)</sup>	$S_{12HG}$	–	-34	-25	dB	High gain mode
	$S_{12LG}$	-9.5	-7.0	-4.0	dB	Low gain mode
Noise figure	$NF_{HG}$	0.9	1.2	1.7	dB	High gain mode
	$NF_{LG}$	3.8	6.8	9.3	dB	Low gain mode
Input return loss <sup>2)</sup>	$S_{11HG}$	–	-20	-10	dB	50 $\Omega$ , high gain mode
	$S_{11LG}$	–	-10	-8	dB	50 $\Omega$ , low gain mode
Output return loss <sup>2)</sup>	$S_{22HG}$	–	-20	-10	dB	50 $\Omega$ , high gain mode
	$S_{22LG}$	–	-11	-9	dB	50 $\Omega$ , low gain mode
Stability factor <sup>3)</sup>	$k$	>1	>2.3	–		DC to 8 GHz; all gain modes
Input compression point <sup>2)</sup>	$IP_{1dBHG}$	-17	-10	–	dBm	High gain mode
	$IP_{1dBLG}$	-10	-2	–	dBm	Low gain mode
Inband IIP3 <sup>2)</sup> $f_1 - f_2 = 1\text{ MHz}$	$IIP3_{HG}$	-9	-2	–	dBm	High gain mode
	$IIP3_{LG}$	-5	7	–	dBm	Low gain mode

1) Performance based on application circuit in Figure 2 on Page 28

2) Verification based on AQL; random production test..

3) Guaranteed by device design; not tested in production.

## 2.11 Measured RF Characteristics UMTS Band 7

**Table 9** Typical Characteristics 2650 MHz Band,  $T_A = 85\text{ °C}$ ,  $V_{CC} = 2.8\text{ V}^{1)2)}$

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Pass band range band VII		2620	–	2690	MHz	–
Current consumption	$I_{CCHG}$	4.6	5.2	5.8	mA	High gain mode
	$I_{CCLG}$	0.2	0.58	0.8	mA	Low gain mode
Gain	$S_{21HG}$	13.1	14.6	16.1	dB	High gain mode
	$S_{21LG}$	-10.4	-7.9	-4.9	dB	Low gain mode
Reverse Isolation	$S_{12HG}$	–	-34	-25	dB	High gain mode
	$S_{12LG}$	-10.4	-7.9	-4.9	dB	Low gain mode
Noise figure	$NF_{HG}$	1.4	1.7	2.2	dB	High gain mode
	$NF_{LG}$	4.9	7.9	10.4	dB	Low gain mode
Input return loss	$S_{11HG}$	–	-16	-10	dB	50 $\Omega$ , high gain mode
	$S_{11LG}$	–	-11	-9	dB	50 $\Omega$ , low gain mode
Output return loss	$S_{22HG}$	–	-20	-10	dB	50 $\Omega$ , high gain mode
	$S_{22LG}$	–	-11	-9	dB	50 $\Omega$ , low gain mode
Stability factor	$k$	>1	>2.3	–		DC to 8 GHz; all gain modes
Input compression point	$IP_{1dBHG}$	-17	-10	–	dBm	High gain mode
	$IP_{1dBLG}$	-10	-2	–	dBm	Low gain mode
Inband IIP3 $f_1 - f_2 = 1\text{ MHz}$	$IIP3_{HG}$	-9	-2	–	dBm	High gain mode
	$IIP3_{LG}$	-3	9	–	dBm	Low gain mode

1) Performance based on application circuit in Figure 2 on Page 28

2) Guaranteed by device design; not tested in production.

## 2.12 Measured RF Characteristics UMTS Band 38

**Table 10** Typical Characteristics 2600 MHz Band,  $T_A = -30\text{ °C}$ ,  $V_{CC} = 2.8\text{ V}^{1)2)}$

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Pass band range band XXXVIII		2570	–	2620	MHz	–
Current consumption	$I_{CCHG}$	2.8	3.4	4.0	mA	High gain mode
	$I_{CCLG}$	0.2	0.5	0.8	mA	Low gain mode
Gain	$S_{21HG}$	14.7	16.2	17.7	dB	High gain mode
	$S_{21LG}$	-8.5	-6.0	-3.0	dB	Low gain mode
Reverse Isolation	$S_{12HG}$	–	-34	-25	dB	High gain mode
	$S_{12LG}$	-8.5	-6.0	-3.0	dB	Low gain mode
Noise figure	$NF_{HG}$	0.6	0.9	1.4	dB	High gain mode
	$NF_{LG}$	3.0	6.0	8.5	dB	Low gain mode
Input return loss	$S_{11HG}$	–	-15	-10	dB	50 $\Omega$ , high gain mode
	$S_{11LG}$	–	-13	-10	dB	50 $\Omega$ , low gain mode
Output return loss	$S_{22HG}$	–	-11	-9	dB	50 $\Omega$ , high gain mode
	$S_{22LG}$	–	-18	-10	dB	50 $\Omega$ , low gain mode
Stability factor	$k$	>1	>2.3	–		DC to 8 GHz; all gain modes
Input compression point	$IP_{1dBHG}$	-16	-9	–	dBm	High gain mode
	$IP_{1dB LG}$	-10	-2	–	dBm	Low gain mode
Inband IIP3 $f_1 - f_2 = 1\text{ MHz}$	$IIP3_{HG}$	-9	-2	–	dBm	High gain mode
	$IIP3_{LG}$	-7	5	–	dBm	Low gain mode

1) Performance based on application circuit in Figure 3 on Page 29

2) Guaranteed by device design; not tested in production.



## 2.13 Measured RF Characteristics UMTS Band 38

**Table 11** Typical Characteristics 2600 MHz Band,  $T_A = 25\text{ °C}$ ,  $V_{CC} = 2.8\text{ V}^{1)2)}$

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Pass band range band XXXVIII		2570	–	2620	MHz	–
Current consumption	$I_{CCHG}$	3.6	4.2	4.8	mA	High gain mode
	$I_{CCLG}$	0.3	0.53	0.7	mA	Low gain mode
Gain	$S_{21HG}$	14.2	15.5	16.8	dB	High gain mode
	$S_{21LG}$	-9.4	-6.9	-3.9	dB	Low gain mode
Reverse Isolation	$S_{12HG}$	–	-34	-25	dB	High gain mode
	$S_{12LG}$	-9.5	-7.0	-4.0	dB	Low gain mode
Noise figure	$NF_{HG}$	0.9	1.2	1.7	dB	High gain mode
	$NF_{LG}$	3.8	6.8	9.3	dB	Low gain mode
Input return loss	$S_{11HG}$	–	-15	-10	dB	50 $\Omega$ , high gain mode
	$S_{11LG}$	–	-11	-9	dB	50 $\Omega$ , low gain mode
Output return loss	$S_{22HG}$	–	-15	-10	dB	50 $\Omega$ , high gain mode
	$S_{22LG}$	–	-13	-10	dB	50 $\Omega$ , low gain mode
Stability factor	$k$	>1	>2.3	–		DC to 8 GHz; all gain modes
Input compression point	$IP_{1dBHG}$	-17	-10	–	dBm	High gain mode
	$IP_{1dB LG}$	-10	-2	–	dBm	Low gain mode
Inband IIP3 $f_1 - f_2 = 1\text{ MHz}$	$IIP3_{HG}$	-9	-2	–	dBm	High gain mode
	$IIP3_{LG}$	-5	7	–	dBm	Low gain mode

1) Performance based on application circuit in Figure 3 on Page 29

2) Guaranteed by device design; not tested in production.

## 2.14 Measured RF Characteristics UMTS Band 38

**Table 12** Typical Characteristics 2600 MHz Band,  $T_A = 85\text{ °C}$ ,  $V_{CC} = 2.8\text{ V}^{1)2)}$

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Pass band range band XXXVIII		2570	–	2620	MHz	–
Current consumption	$I_{CCHG}$	4.6	5.2	5.8	mA	High gain mode
	$I_{CCLG}$	0.2	0.58	0.8	mA	Low gain mode
Gain	$S_{21HG}$	13.4	14.9	16.4	dB	High gain mode
	$S_{21LG}$	-9.9	-7.4	-4.4	dB	Low gain mode
Reverse Isolation	$S_{12HG}$	–	-34	-25	dB	High gain mode
	$S_{12LG}$	-9.9	-7.4	-4.4	dB	Low gain mode
Noise figure	$NF_{HG}$	1.4	1.7	2.2	dB	High gain mode
	$NF_{LG}$	4.4	7.4	-9.9	dB	Low gain mode
Input return loss	$S_{11HG}$	–	-16	-10	dB	50 $\Omega$ , high gain mode
	$S_{11LG}$	–	-13	-10	dB	50 $\Omega$ , low gain mode
Output return loss	$S_{22HG}$	–	-16	-10	dB	50 $\Omega$ , high gain mode
	$S_{22LG}$	–	-15	-10	dB	50 $\Omega$ , low gain mode
Stability factor	$k$	>1	>2.3	–		DC to 8 GHz; all gain modes
Input compression point	$IP_{1dBHG}$	-18	-11	–	dBm	High gain mode
	$IP_{1dB LG}$	-10	-2	–	dBm	Low gain mode
Inband IIP3 $f_1 - f_2 = 1\text{ MHz}$	$IIP3_{HG}$	-9	-2	–	dBm	High gain mode
	$IIP3_{LG}$	-3	9	–	dBm	Low gain mode

1) Performance based on application circuit in Figure 3 on Page 29

2) Guaranteed by device design; not tested in production.

## 2.15 Measured RF Characteristics UMTS Band 40

**Table 13** Typical Characteristics 2300 MHz Band,  $T_A = -30\text{ °C}$ ,  $V_{CC} = 2.8\text{ V}^{1)2)}$

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Pass band range band XL		2300	–	2400	MHz	–
Current consumption	$I_{CCHG}$	2.8	3.4	4.0	mA	High gain mode
	$I_{CCLG}$	0.2	0.5	0.8	mA	Low gain mode
Gain	$S_{21HG}$	15.8	17.3	18.8	dB	High gain mode
	$S_{21LG}$	-8.7	-6.2	-3.2	dB	Low gain mode
Reverse Isolation	$S_{12HG}$	–	-35	-25	dB	High gain mode
	$S_{12LG}$	-8.7	-6.2	-3.2	dB	Low gain mode
Noise figure	$NF_{HG}$	0.6	0.9	1.4	dB	High gain mode
	$NF_{LG}$	3.2	6.2	8.7	dB	Low gain mode
Input return loss	$S_{11HG}$	–	-17	-10	dB	50 $\Omega$ , high gain mode
	$S_{11LG}$	–	-13	-10	dB	50 $\Omega$ , low gain mode
Output return loss	$S_{22HG}$	–	-16	-10	dB	50 $\Omega$ , high gain mode
	$S_{22LG}$	–	-14	-10	dB	50 $\Omega$ , low gain mode
Stability factor	$k$	>1	>2.3	–		DC to 8 GHz; all gain modes
Input compression point	$IP_{1dBHG}$	-17	-10	–	dBm	High gain mode
	$IP_{1dB LG}$	-10	-2	–	dBm	Low gain mode
Inband IIP3 $f_1 - f_2 = 1\text{ MHz}$	$IIP3_{HG}$	-9	-2	–	dBm	High gain mode
	$IIP3_{LG}$	-7	5	–	dBm	Low gain mode

1) Performance based on application circuit in Figure 4 on Page 30

2) Guaranteed by device design; not tested in production.

## 2.16 Measured RF Characteristics UMTS Band 40

**Table 14** Typical Characteristics 2300 MHz Band,  $T_A = 25\text{ °C}$ ,  $V_{CC} = 2.8\text{ V}$ <sup>1)2)</sup>

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Pass band range band XL		2300	–	2400	MHz	–
Current consumption	$I_{CCHG}$	3.6	4.2	4.8	mA	High gain mode
	$I_{CCLG}$	0.3	0.53	0.7	mA	Low gain mode
Gain	$S_{21HG}$	15.5	16.8	18.1	dB	High gain mode
	$S_{21LG}$	-9.7	-7.2	-4.2	dB	Low gain mode
Reverse Isolation	$S_{12HG}$	–	-35	-25	dB	High gain mode
	$S_{12LG}$	-9.5	-7.0	-4.0	dB	Low gain mode
Noise figure	$NF_{HG}$	0.9	1.2	1.7	dB	High gain mode
	$NF_{LG}$	4.0	7.0	9.5	dB	Low gain mode
Input return loss	$S_{11HG}$	–	-23	-10	dB	50 $\Omega$ , high gain mode
	$S_{11LG}$	–	-12	-10	dB	50 $\Omega$ , low gain mode
Output return loss	$S_{22HG}$	–	-15	-10	dB	50 $\Omega$ , high gain mode
	$S_{22LG}$	–	-12	-10	dB	50 $\Omega$ , low gain mode
Stability factor	$k$	>1	>2.3	–		DC to 8 GHz; all gain modes
Input compression point	$IP_{1dBHG}$	-18	-11	–	dBm	High gain mode
	$IP_{1dBLG}$	-10	-2	–	dBm	Low gain mode
Inband IIP3 $f_1 - f_2 = 1\text{ MHz}$	$IIP3_{HG}$	-9	-2	–	dBm	High gain mode
	$IIP3_{LG}$	-5	7	–	dBm	Low gain mode

1) Performance based on application circuit in Figure 4 on Page 30

2) Guaranteed by device design; not tested in production.

## 2.17 Measured RF Characteristics UMTS Band 40

**Table 15** Typical Characteristics 2300 MHz Band,  $T_A = 85\text{ °C}$ ,  $V_{CC} = 2.8\text{ V}^{1)2)}$

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Pass band range band XL		2300	–	2400	MHz	–
Current consumption	$I_{CCHG}$	4.6	5.2	5.8	mA	High gain mode
	$I_{CCLG}$	0.2	0.58	0.8	mA	Low gain mode
Gain	$S_{21HG}$	14.5	16.0	17.5	dB	High gain mode
	$S_{21LG}$	-10.1	-7.6	-4.6	dB	Low gain mode
Reverse Isolation	$S_{12HG}$	–	-35	-25	dB	High gain mode
	$S_{12LG}$	-10.1	-7.6	-4.6	dB	Low gain mode
Noise figure	$NF_{HG}$	1.2	1.5	2.0	dB	High gain mode
	$NF_{LG}$	4.6	7.6	10.1	dB	Low gain mode
Input return loss	$S_{11HG}$	–	-18	-10	dB	50 $\Omega$ , high gain mode
	$S_{11LG}$	–	-13	-10	dB	50 $\Omega$ , low gain mode
Output return loss	$S_{22HG}$	–	-17	-10	dB	50 $\Omega$ , high gain mode
	$S_{22LG}$	–	-13	-10	dB	50 $\Omega$ , low gain mode
Stability factor	$k$	>1	>2.3	–		DC to 8 GHz; all gain modes
Input compression point	$IP_{1dBHG}$	-19	-12	–	dBm	High gain mode
	$IP_{1dBLG}$	-10	-2	–	dBm	Low gain mode
Inband IIP3 $f_1 - f_2 = 1\text{ MHz}$	$IIP3_{HG}$	-9	-2	–	dBm	High gain mode
	$IIP3_{LG}$	-3	9	–	dBm	Low gain mode

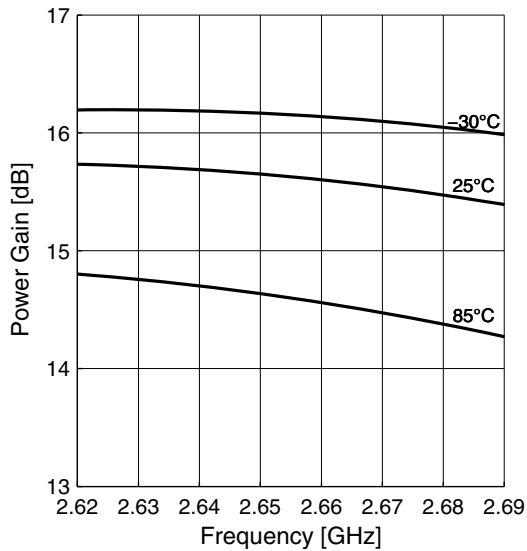
1) Performance based on application circuit in Figure 4 on Page 30

2) Guaranteed by device design; not tested in production.

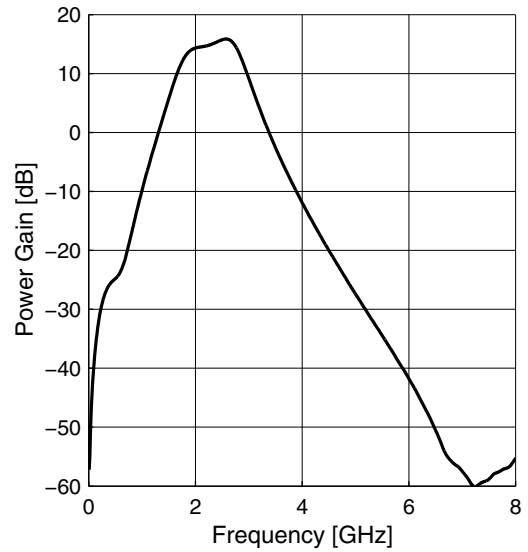
### 2.18 Measured Performance Band 7 Application High Gain Mode vs. Frequency

$T_A = 25\text{ }^\circ\text{C}$ ,  $V_{CC} = 2.8\text{ V}$ ,  $V_{GS} = 2.8\text{ V}$ ,  $V_{EN} = 2.8\text{ V}$

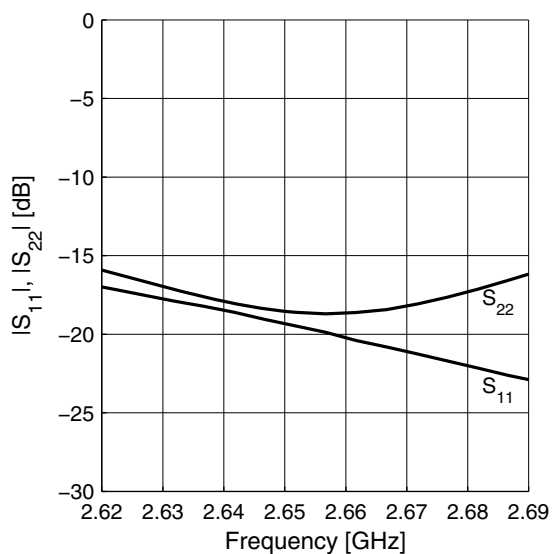
Power Gain  $|S_{21}| = f(f)$



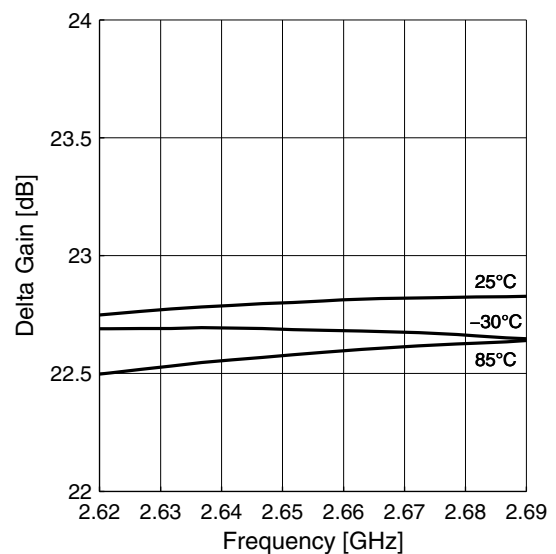
Power Gain wideband  $|S_{21}| = f(f)$



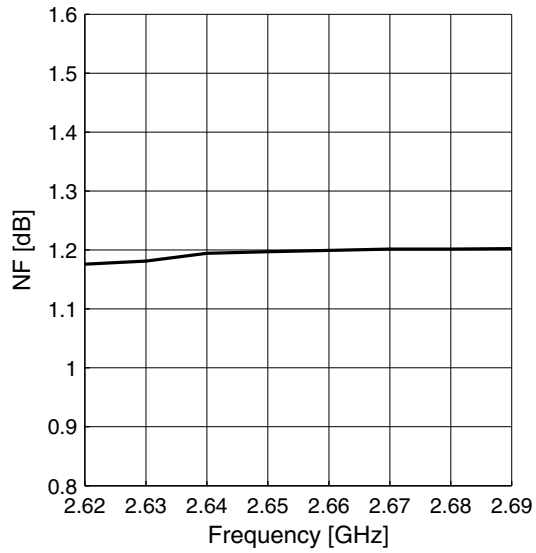
Matching  $|S_{11}| = f(f)$ ,  $|S_{22}| = f(f)$



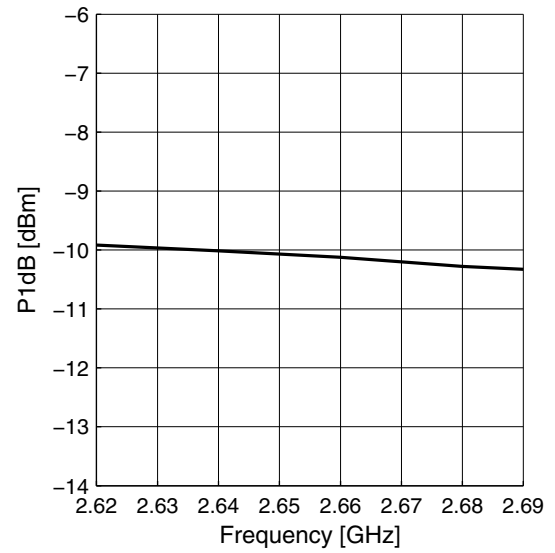
Gainstep HG-LG  $\Delta S_{21} = f(f)$



**Noise Figure  $NF = f(f)$**



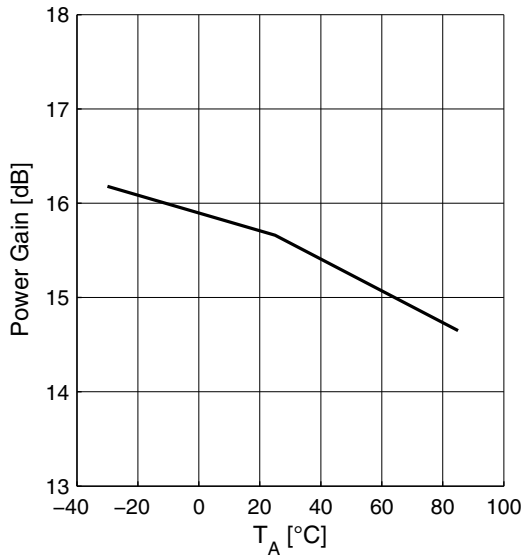
**Input Compression  $P1dB = f(f)$**



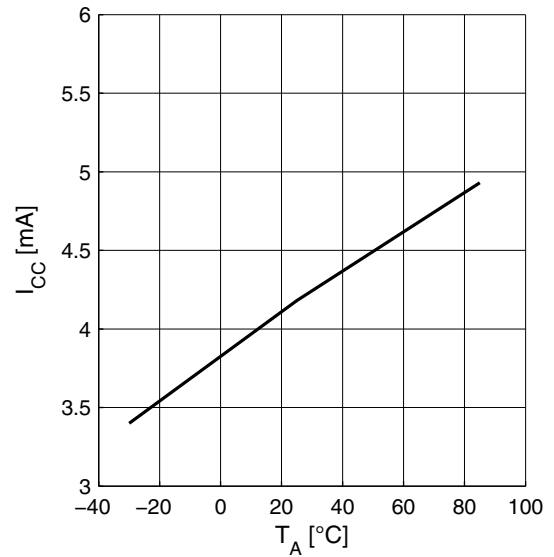
### 2.19 Measured Performance Band 7 Application High Gain Mode vs. Temperature

$T_A = 25\text{ }^\circ\text{C}$ ,  $V_{CC} = 2.8\text{ V}$ ,  $V_{GS} = 2.8\text{ V}$ ,  $V_{EN} = 2.8\text{ V}$ ,  $f = 2650\text{ MHz}$

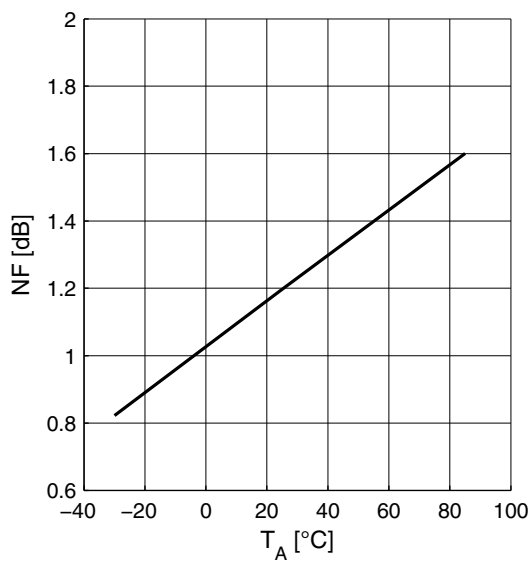
Power Gain  $|S_{21}| = f(T_A)$



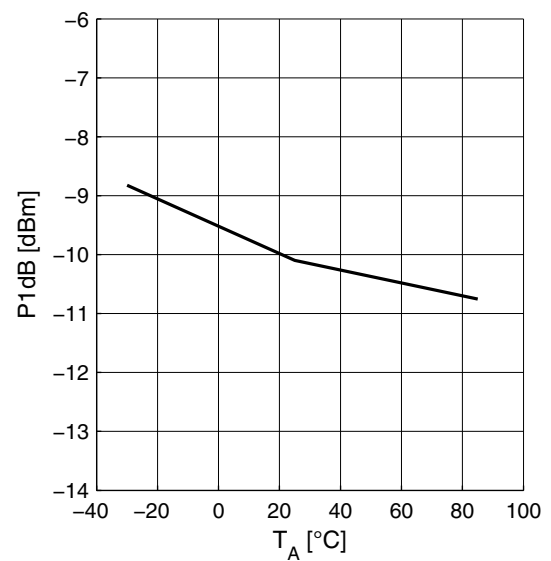
Supply Current  $I_{CC} = f(T_A)$



Noise Figure  $NF = f(T_A)$



Input Compression  $P1dB = f(T_A)$

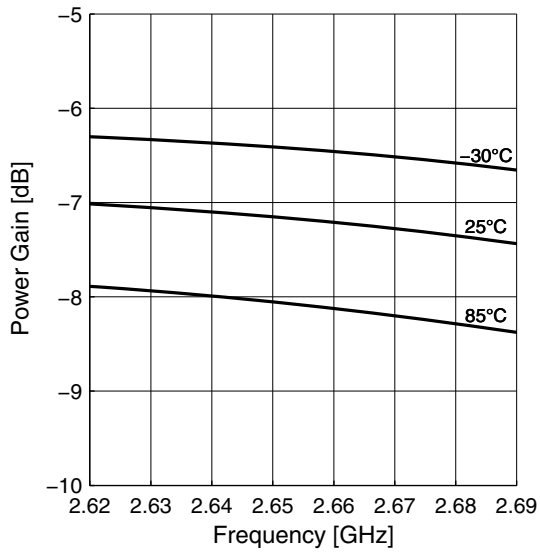




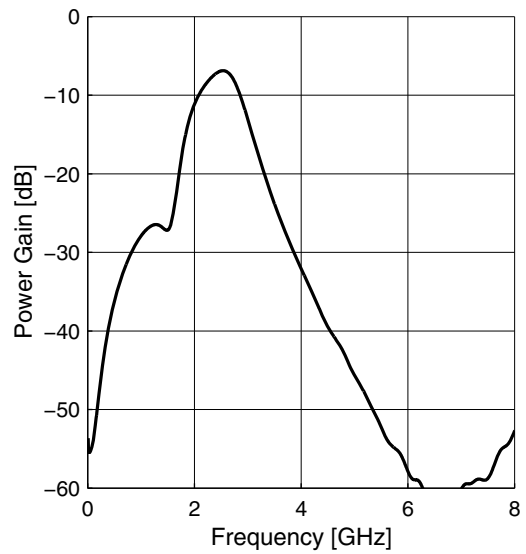
### 2.20 Measured Performance Band 7 Application Low Gain Mode vs. Frequency

$T_A = 25\text{ }^\circ\text{C}$ ,  $V_{CC} = 2.8\text{ V}$ ,  $V_{GS} = 0\text{ V}$ ,  $V_{EN} = 2.8\text{ V}$

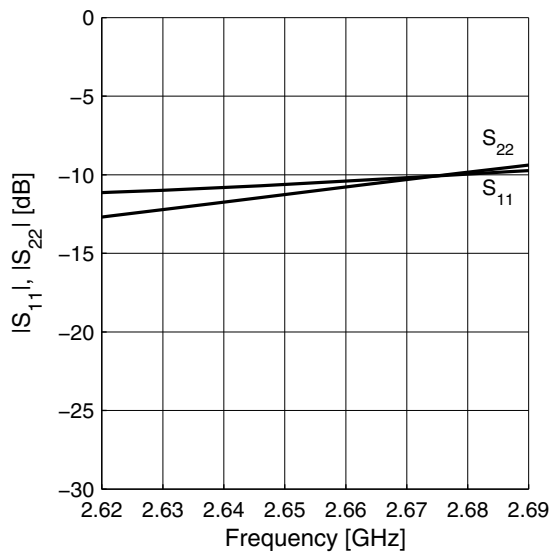
Power Gain  $|S_{21}| = f(f)$



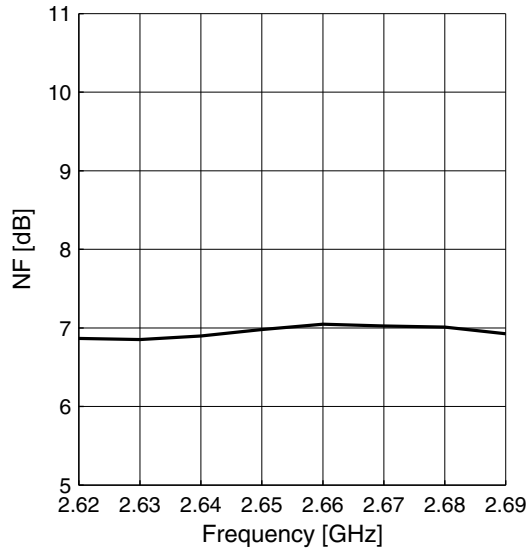
Power Gain wideband  $|S_{21}| = f(f)$



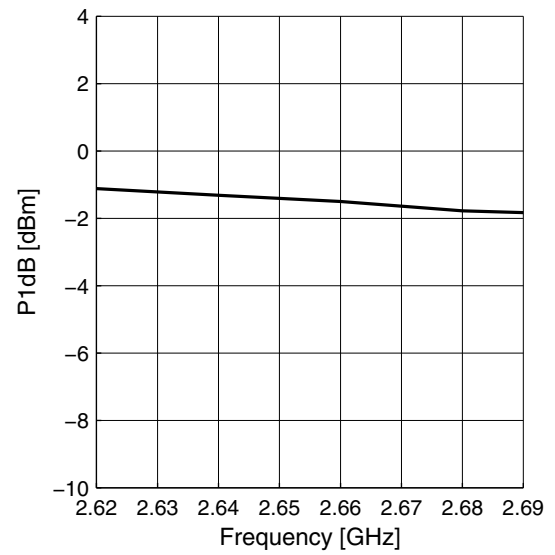
Matching  $|S_{11}| = f(f)$ ,  $|S_{22}| = f(f)$



**Noise Figure  $NF = f(f)$**



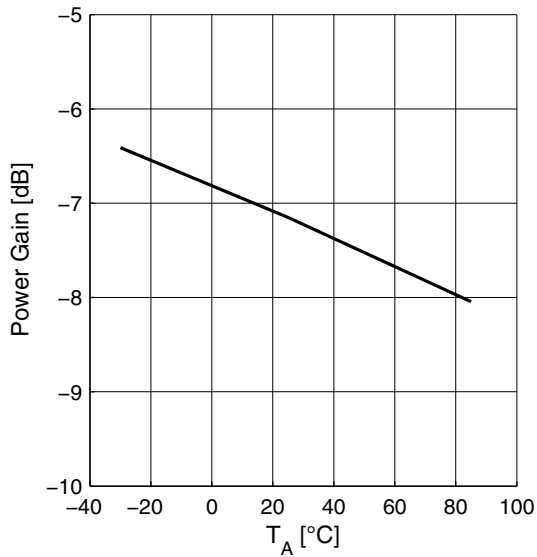
**Input Compression  $P1dB = f(f)$**



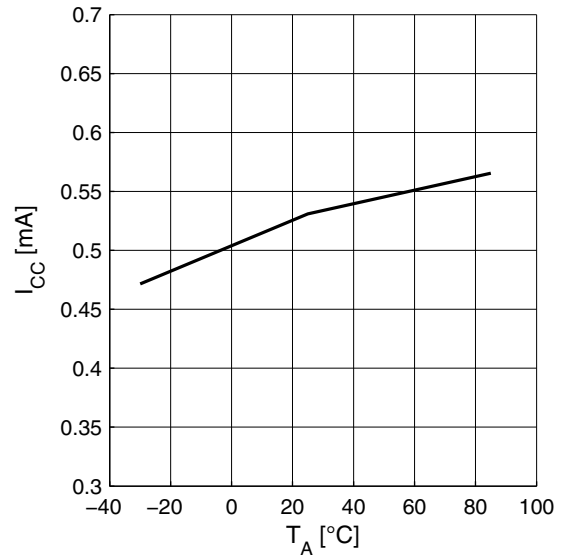
### 2.21 Measured Performance Band 7 Application Low Gain Mode vs. Temperature

$T_A = 25\text{ }^\circ\text{C}$ ,  $V_{CC} = 2.8\text{ V}$ ,  $V_{GS} = 0\text{ V}$ ,  $V_{EN} = 2.8\text{ V}$ ,  $f = 2650\text{ MHz}$

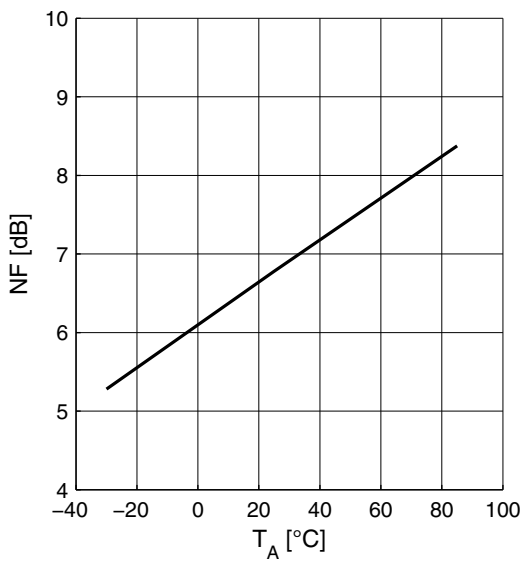
Power Gain  $|S_{21}| = f(T_A)$



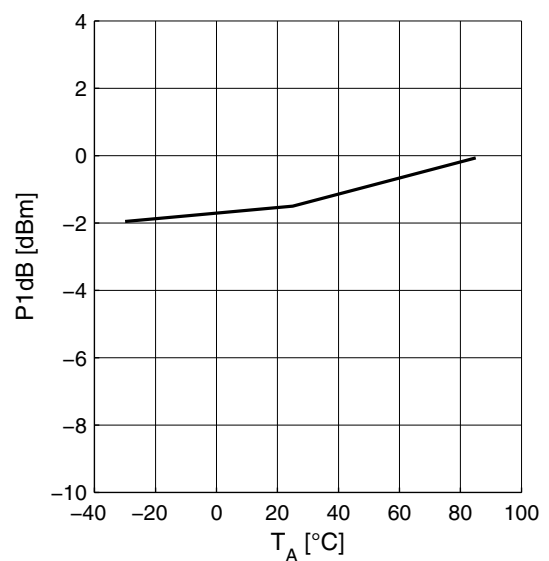
Supply Current  $I_{CC} = f(T_A)$



Noise Figure  $NF = f(T_A)$

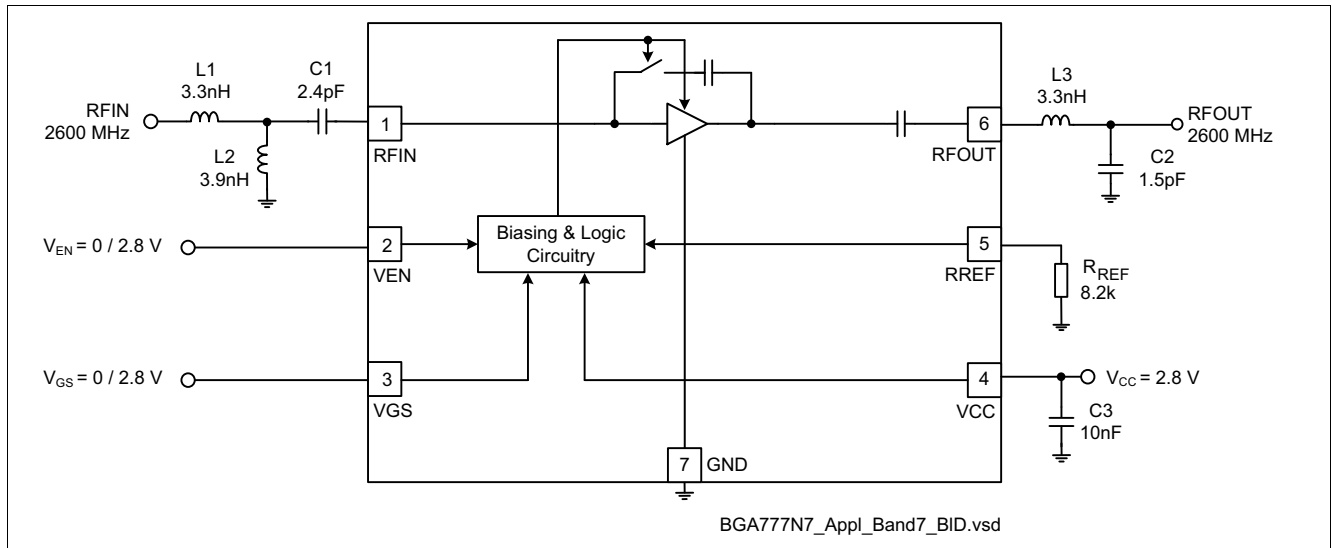


Input Compression  $P1dB = f(T_A)$



### 3 Application Circuit and Block Diagram

#### 3.1 UMTS Band 7 Application Circuit Schematic



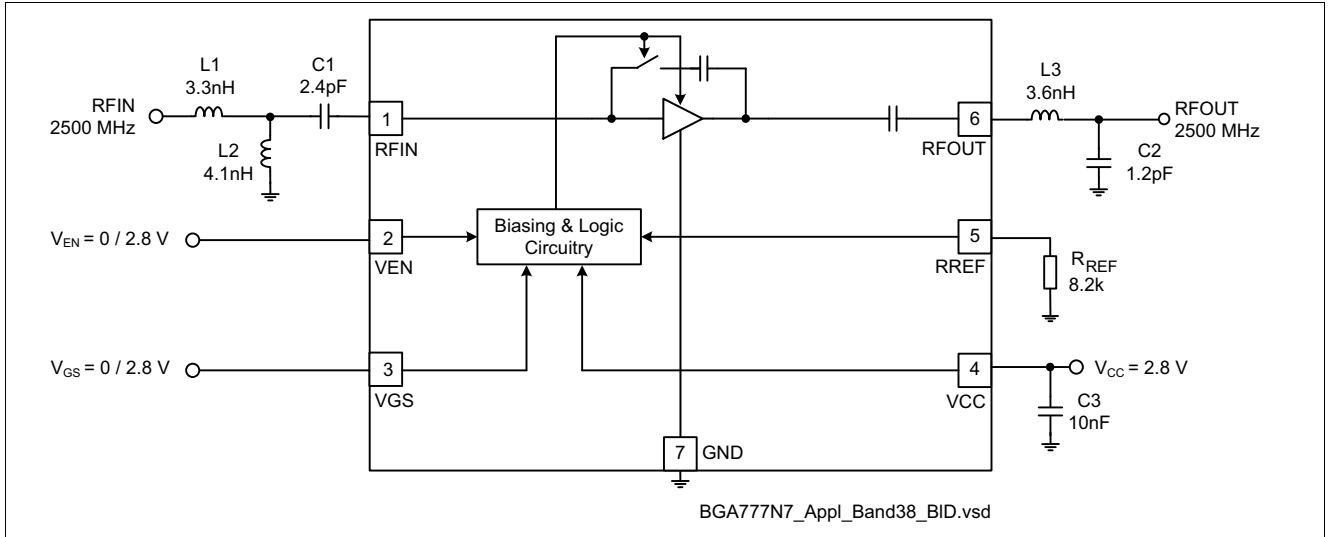
**Figure 2 Application Circuit with Chip Outline (Top View)**

*Note: Package paddle (Pin 0) has to be RF grounded.*

**Table 16 Bill of Materials**

Part Number	Part Type	Manufacturer	Size	Comment
L1 ... L3	Chip inductor	Various	0402	Wirewound, Q ≈ 50
C1 ... C3	Chip capacitor	Various	0402	
R <sub>REF</sub>	Chip resistor	Various	0402	

### 3.2 UMTS Band 38 Application Circuit Schematic



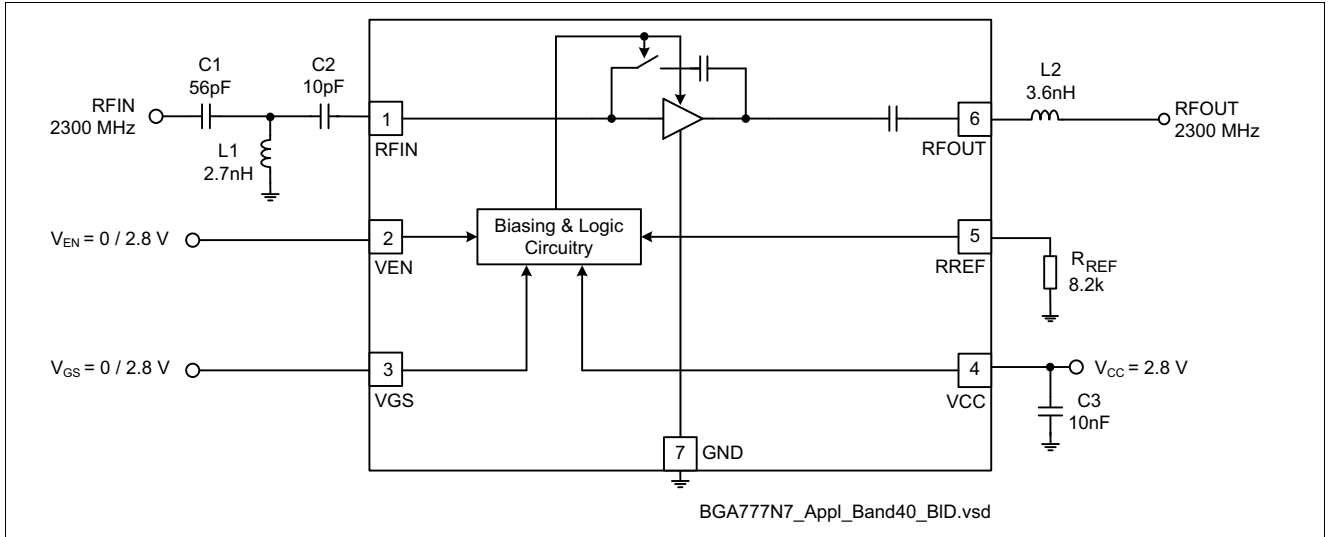
**Figure 3 Application Circuit with Chip Outline (Top View)**

*Note: Package paddle (Pin 0) has to be RF grounded.*

**Table 17 Bill of Materials**

Part Number	Part Type	Manufacturer	Size	Comment
L1 ... L3	Chip inductor	Various	0402	Wirewound, $Q \approx 50$
C1 ... C3	Chip capacitor	Various	0402	
R <sub>REF</sub>	Chip resistor	Various	0402	

### 3.3 UMTS Band 40 Application Circuit Schematic



**Figure 4 Application Circuit with Chip Outline (Top View)**

Note: Package paddle (Pin 0) has to be RF grounded.

**Table 18 Bill of Materials**

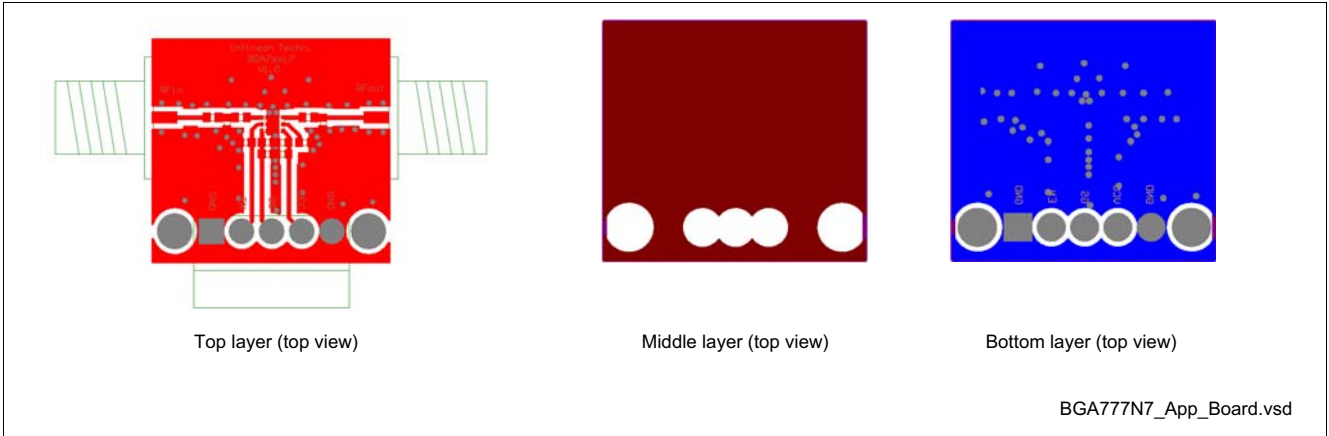
Part Number	Part Type	Manufacturer	Size	Comment
L1 ... L2	Chip inductor	Various	0402	Wirewound, Q ≈ 50
C1 ... C3	Chip capacitor	Various	0402	
R <sub>REF</sub>	Chip resistor	Various	0402	

### 3.4 Pin Definition

**Table 19 Pin Definition and Function**

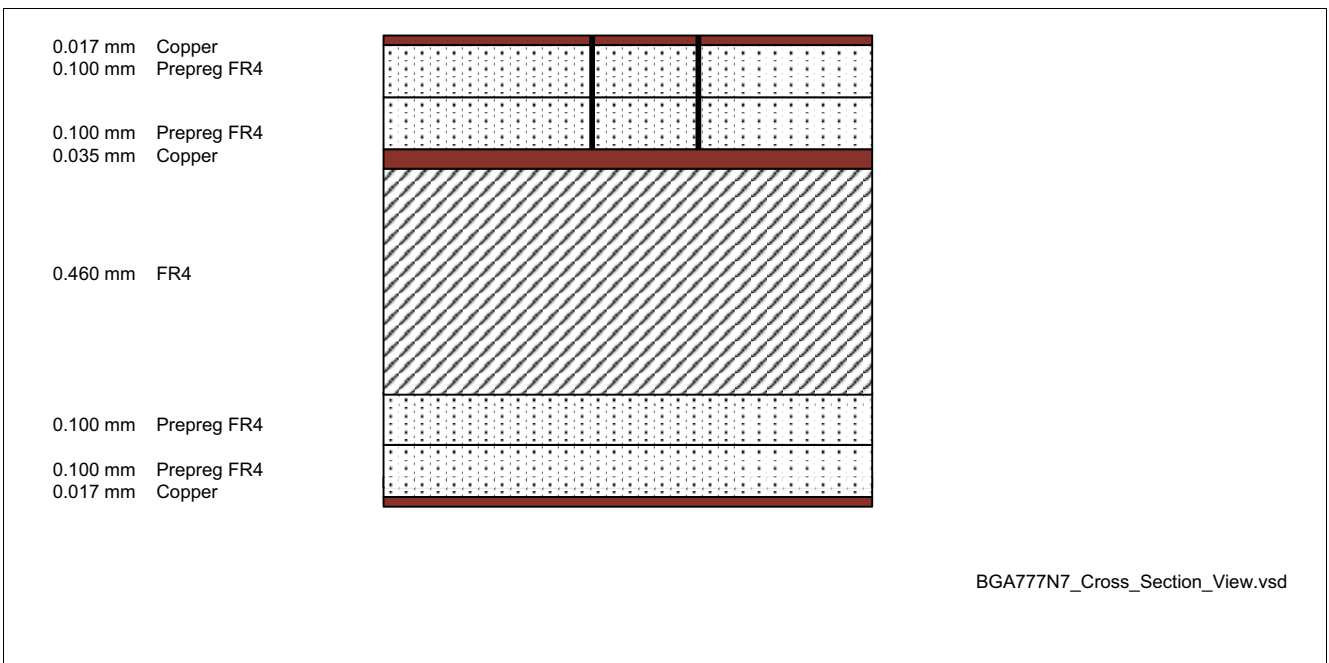
Pin Number	Symbol	Function
1	RFIN	LNA input (2600 MHz)
2	VEN	Band select control
3	VGS	Gain step control
4	VCC	Supply voltage
5	R <sub>REF</sub>	Bias current reference resistor (high gain mode)
6	RFOUT	LNA output (2600 MHz)
7	GND	Package paddle; ground connection for LNA and control circuitry

### 3.5 Application Board

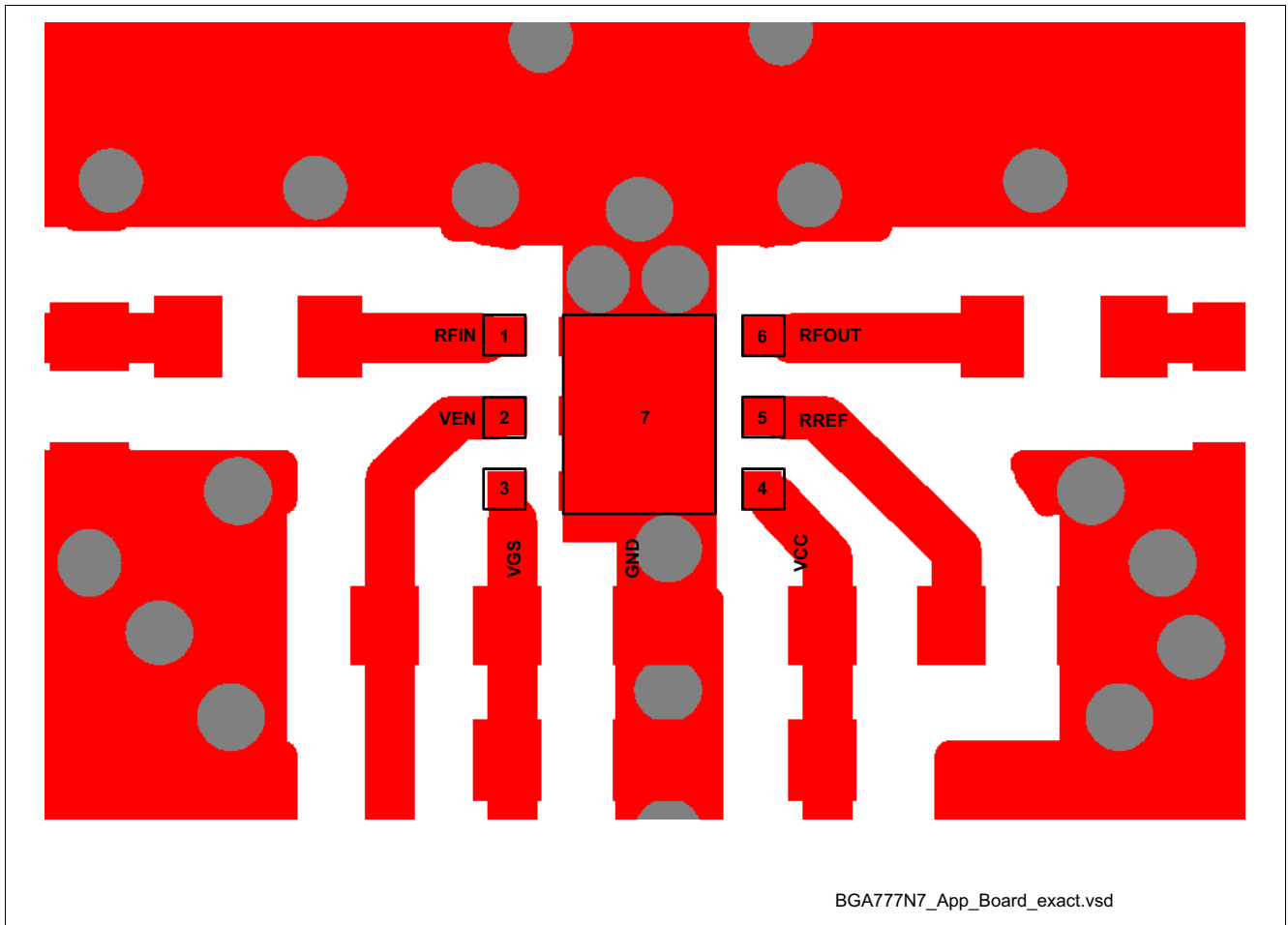


**Figure 5 Application Board Layout on 3-Layer FR4**

*Note: Top layer thickness: 0.2 mm, bottom layer thickness: 0.8 mm, 17  $\mu$ m Cu metallization, gold plated. Board size: 21 x 19mm.*



**Figure 6 Cross-Section View of Application Board**



**Figure 7** Detail of Application Board Layout

*Note: In order to achieve the same performance as given in this datasheet please follow the suggested PCB-layout as closely as possible. The position of the GND via is critical for RF performance.*



## 4 Physical Characteristics

### 4.1 Package Footprint

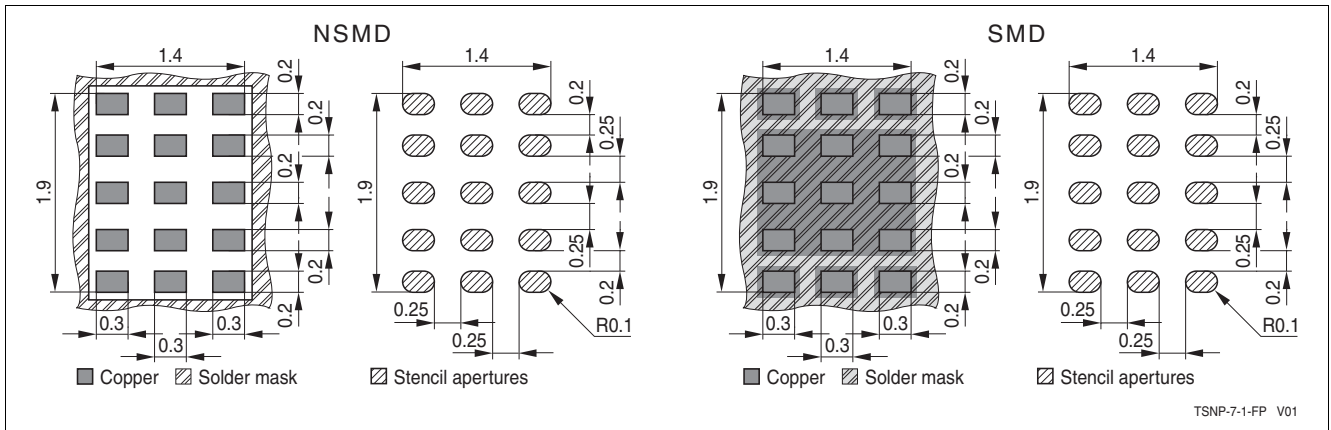


Figure 8 Footprint Recommendation 1 for the TSNP-7-1 Package

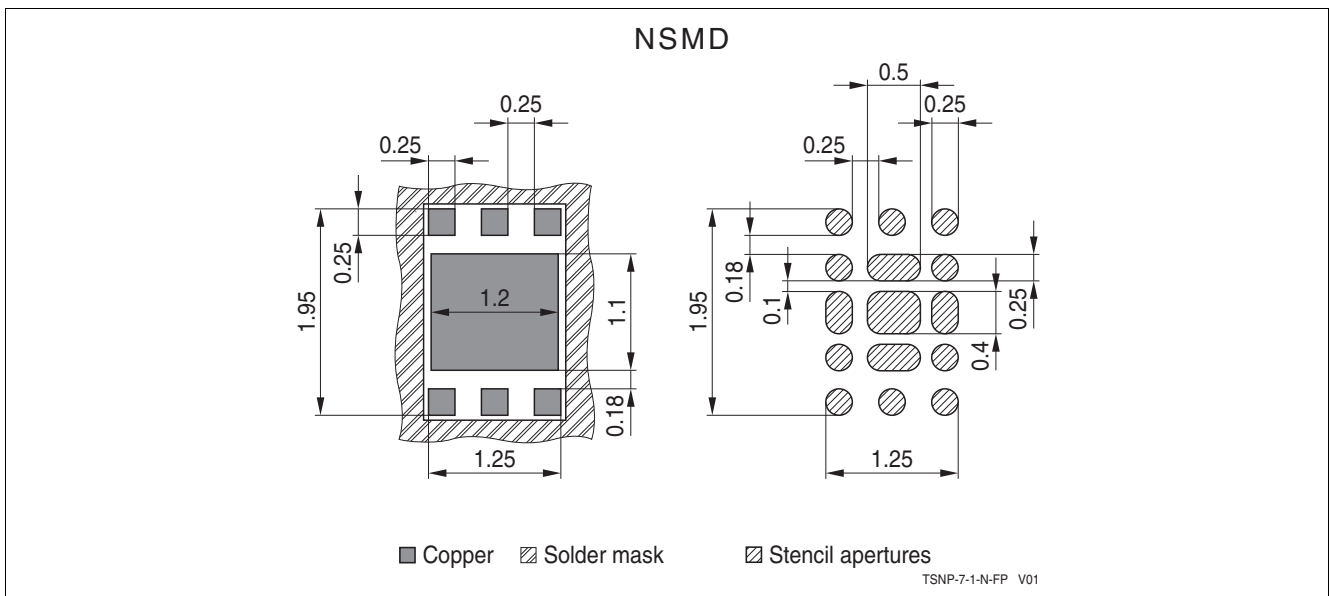


Figure 9 Footprint Recommendation 2 for the TSNP-7-1 Package

## 4.2 Package Dimensions

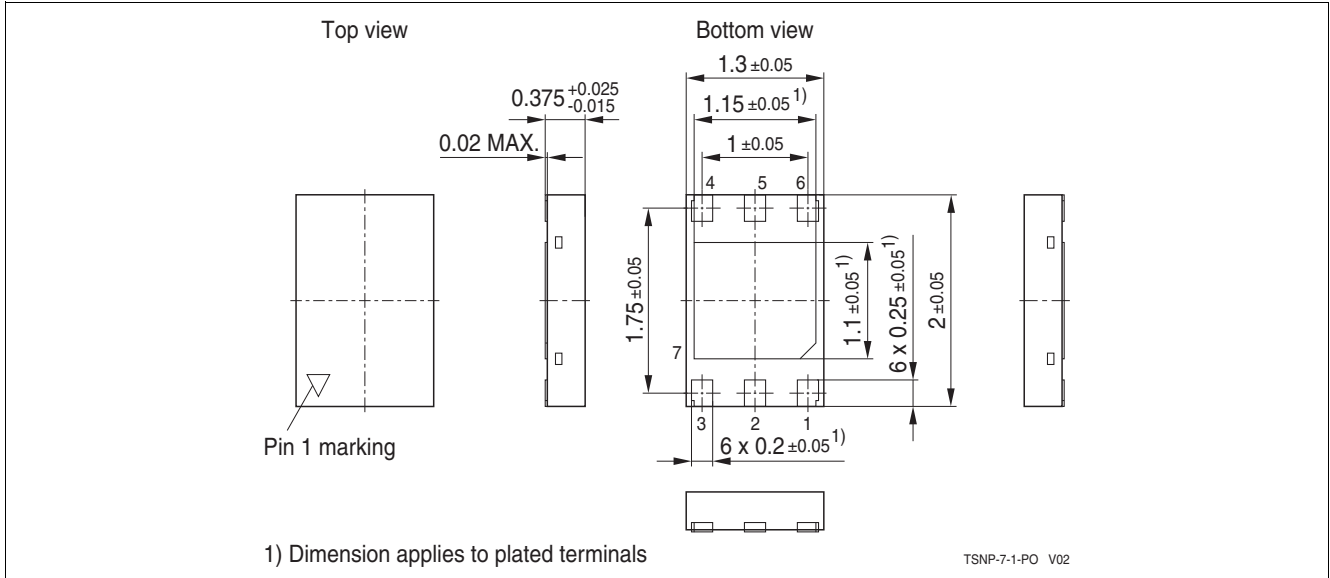


Figure 10 Package Outline (top, side and bottom view)

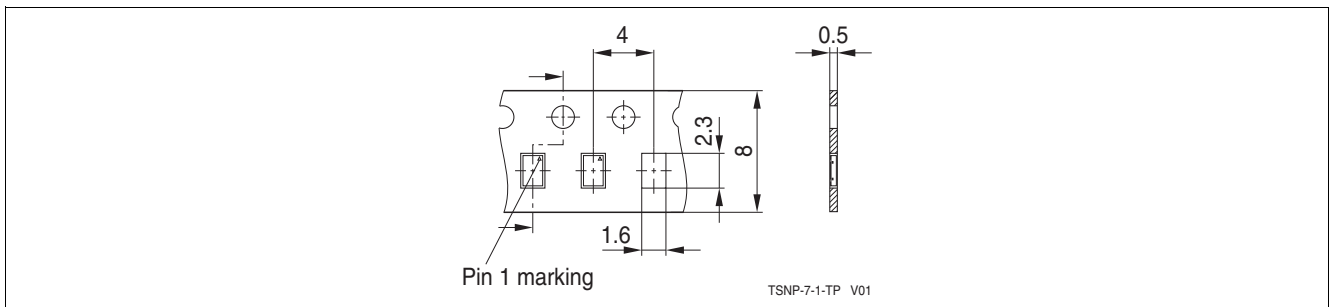


Figure 11 Tape & Reel Dimensions

## 4.3 Product Marking Pattern

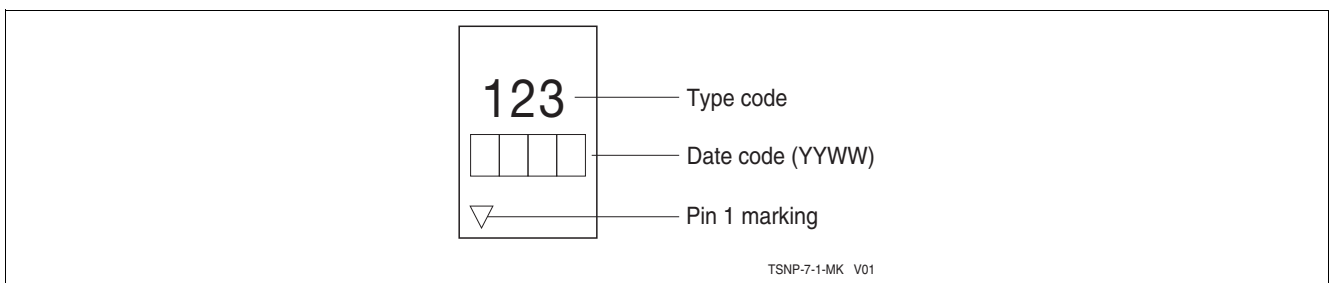


Figure 12 Marking Pattern (top view)

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